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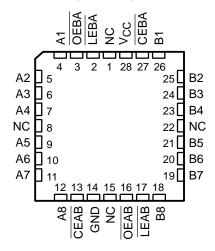
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Unregulated Battery Operation Down to 2.7 V
- I_{off} and Power-Up 3-State Support Hot Insertion

SN54LVTH543 . . . JT OR W PACKAGE SN74LVTH543 . . . DB, DGV, DW, NS, OR PW PACKAGE (TOP VIEW)

LEBA [1	\bigcup_{24}] v _{cc}
OEBA [2	23	CEBA
A1 [3	22] B1
A2 [4	21	B2
A3 [5	20] B3
A4 [6	19] B4
A5 [18	B5
A6 [8	17] B6
A7 [9	16] B7
A8 [10	15	B8
CEAB [11	14	LEAB
GND [12	13	OEAB

- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

SN54LVTH543 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

These octal transceivers are designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

ORDERING INFORMATION

TA	PACK	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	SOIC - DW	Tube	SN74LVTH543DW	LVTH543	
	30IC = DW	Tape and reel	SN74LVTH543DWR	LV 1 11343	
-40°C to 85°C	SOP - NS	Tape and reel	SN74LVTH543NSR	LVTH543	
	SSOP – DB	Tape and reel	SN74LVTH543DBR	LXH543	
	TSSOP – PW Tape and reel		SN74LVTH543PWR	LXH543	
	TVSOP – DGV Tape and reel		SN74LVTH543DGVR	LXH543	
	CDIP – JT	Tube	SNJ54LVTH543JT	SNJ54LVTH543JT	
–55°C to 125°C	CFP – W	Tube	SNJ54LVTH543W	SNJ54LVTH543W	
	LCCC – FK	Tube	SNJ54LVTH543FK	SNJ54LVTH543FK	

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

The 'LVTH543 devices contain two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch-enable (LEAB or LEBA) and output-enable (OEAB or OEBA) inputs are provided for each register, to permit independent control in either direction of data flow.

The A-to-B enable (CEAB) input must be low to enter data from A or to output data from B. If CEAB is low and LEAB is low, the A-to-B latches are transparent; a subsequent low-to-high transition of LEAB puts the A latches in the storage mode. With CEAB and OEAB both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar, but requires using the CEBA, LEBA, and OEBA inputs.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

When V_{CC} is between 0 and 1.5 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

FUNCTION TABLE†

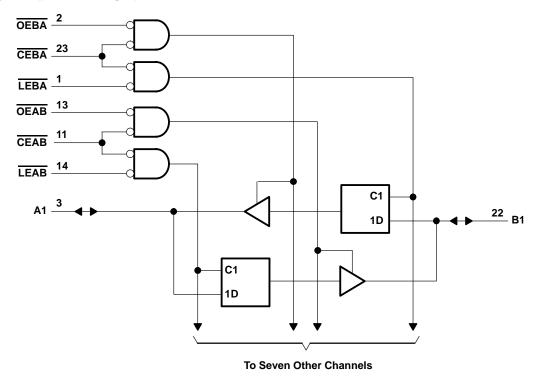
	OUTPUT			
CEAB	LEAB	OEAB	Α	В
Н	Χ	Х	Χ	Z
Х	Χ	Н	Χ	Z
L	Н	L	Χ	в ₀ ‡
L	L	L	L	L
L	L	L	Н	Н

[†] A-to-B data flow is shown; B-to-A flow control is the same, except that it uses CEBA, LEBA, and OEBA.



[‡]Output level before the indicated steady-state input conditions were established

logic diagram (positive logic)



Pin numbers shown are for the DB, DGV, DW, JT, NS, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		
Input voltage range, V _I (see Note 1)		0.5 V to 7 V
Voltage range applied to any output in the high-	-impedance	
or power-off state, V _O (see Note 1)		–0.5 V to 7 V
Voltage range applied to any output in the high	state, VO (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Current into any output in the low state, IO: SN	54LVTH543	96 mA
		128 mA
Current into any output in the high state, IO (see	e Note 2): SN54LVTH543	48 mA
_	SN74LVTH543	64 mA
Input clamp current, I _{IK} (V _I < 0)		
Output clamp current, IOK (VO < 0)		
Package thermal impedance, θ _{JA} (see Note 3):	DB package	63°C/W
,		86°C/W
	DW package	46°C/W
	NS package	65°C/W
		88°C/W
Storage temperature range, T _{stq}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

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recommended operating conditions (see Note 4)

			SN54LV	TH543	SN74LVTH54		LINUT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage		2	3	2		V
V _{IL}	Low-level input voltage			0.8		8.0	V
٧ _I	Input voltage		4	5.5		5.5	V
IOH	High-level output current		7.	-24		-32	mA
loL	Low-level output current		02	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	70,	10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
T _A	Operating free-air temperature	_	-55	125	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST O	ONDITIONS	SN	54LVTH	543	SN	74LVTH5	643	LINUT	
PAR	KAWETER	lEST C	ONDITIONS	MIN	TYP	MAX	MIN	TYP [†]	MAX	UNIT	
VIK		$V_{CC} = 2.7 \text{ V},$	I _I = -18 mA			-1.2			-1.2	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0	.2		VCC-0	.2			
V		$V_{CC} = 2.7 \text{ V},$	$I_{OH} = -8 \text{ mA}$	2.4			2.4			V	
VOH		V _{CC} = 3 V	$I_{OH} = -24 \text{ mA}$	2						V	
		VCC = 3 V	$I_{OH} = -32 \text{ mA}$	μΑ V _{CC} -0.2 V _{CC} -0.2 A 2.4 2.4 hA 2 hA 2 A 0.2 0.5 A 0.5 0.5 A 0.5 0.5 A 0.5 0.5 A 0.5 0.5 A 1 0 10 10							
		V _{CC} = 2.7 V	I _{OL} = 100 μA			0.2			0.2		
		VCC = 2.7 V	I _{OL} = 24 mA			0.5			0.5		
Voi			I _{OL} = 16 mA			0.4			0.4	V	
VOL	V _{CC} = 3 V	I _{OL} = 32 mA			0.5			0.5	V		
		VCC = 3 V	$I_{OL} = 48 \text{ mA}$			0.55				1 1	
Vo		$I_{OL} = 64 \text{ mA}$			Ż.			0.55			
	Control inputs	$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND		Š	±1			±1		
	Control inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V		24	10			10		
Ц	A or B ports‡	V _{CC} = 3.6 V	V _I = 5.5 V		1	20			20	μΑ	
			VI = VCC		3	1			1		
			V _I = 0	-5			-5				
l _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V	Q					±100	μΑ	
		V _{CC} = 3 V	V _I = 0.8 V	75			75				
I _{I(hold)}	A or B ports		V _I = 2 V	-75	– 75			– 75			
		V _{CC} = 3.6 V§	$V_{I} = 0 \text{ to } 3.6 \text{ V}$						±500		
lozpu		$\frac{V_{CC}}{OE} = 0$ to 1.5 V, $V_{O} = 0$	0.5 to 3 V,			±100*			±100	μΑ	
lozpd		$\frac{V_{CC}}{OE}$ = 1.5 V to 0, V _O = $\frac{V_{CC}}{OE}$ = don't care	0.5 to 3 V,			±100*			±100	μΑ	
Icc			Outputs high			0.19			0.19		
		$V_{CC} = 3.6 \text{ V, I}_{O} = 0,$ $V_{I} = V_{CC} \text{ or GND}$	Outputs low		5		5			mA	
		1 - 1 - 100 31 3145	Outputs disabled			0.19			0.19	<u> </u>	
ΔICC¶		$V_{CC} = 3 \text{ V to } 3.6 \text{ V, On}$ Other inputs at V_{CC} or				0.2			0.2	mA	
Ci		V _I = 3 V or 0			4			4		pF	
C _{io}		V _O = 3 V or 0			9			9		pF	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. ‡ Unused terminals are at V_{CC} or GND.

[§] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

 $[\]P$ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V $_{
m CC}$ or GND.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

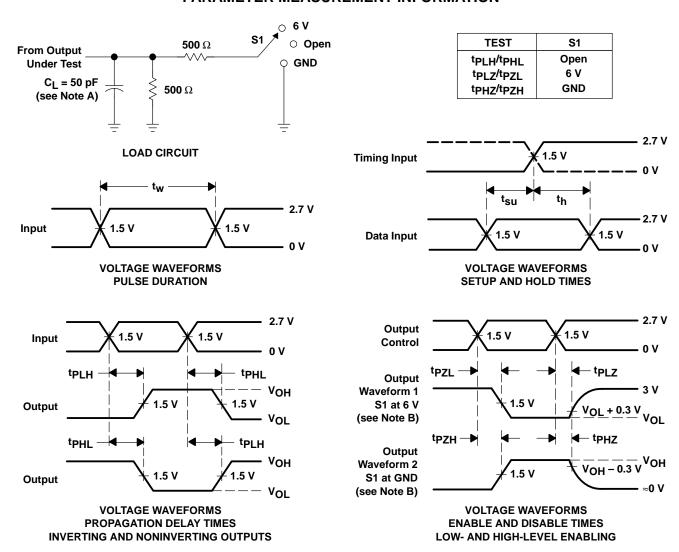
				SN54L\	/TH543			SN74L\	/TH543			
				V _{CC} =		VCC =	2.7 V	V _{CC} =		VCC =	2.7 V	UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _W	Pulse duration, LEAB or LEBA low		3.3		3.3		3.3		3.3		ns	
		A or B before	Data high	0.4		0.4		0.4		0.4		
t Catum time	LEAB or LEBA↑	Data low	1		1.5		1		1.5			
เรน	t _{Su} Setup time	A or B before CEAB or CEBA↑	Data high	0.2	4	0.2		0.2		0.2		ns
			Data low	0.7	5	1.2		0.7		1.2		
		A or B after	Data high	1.5	77	0.6		1.5		0.6		
t Hald Care	LEAB or LEBA↑	Data low	1.3	30	1.5		1.3		1.5			
^t h	t _h Hold time	A or B after	Data high	1.6	D	0.5		1.6		0.5		ns
		CEAB or CEBA↑	Data low	1.4		1.6		1.4		1.6		

switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

				SN54LVTH543				SN74LVTH543					
PARAMETER	FROM (INPUT)	TO (OUTPUT)	00 .		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT	
			MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX		
t _{PLH}	A or B	B or A	1.2	3.9		4.5	1.3	2.5	3.7		4.3	ns	
t _{PHL}	AOIB	BULA	1.2	3.9		4.5	1.3	2.5	3.7		4.3	115	
t _{PLH}	ĪĒ	A or B	1.2	5.1	_	6.1	1.3	2.9	4.7		5.9	ns	
t _{PHL}	LE	AUID	1.2	5.1	14	6.1	1.3	2.9	4.7		5.9	115	
^t PZH		A or B	1	5.1	13/	6.4	1.1	2.9	4.9		6.2	20	
t _{PZL}	ŌĒ	OE	AUIB	1	5.1	4	6.4	1.1	3.2	4.9		6.2	ns
t _{PHZ}	ŌĒ	A or B	1.9	5.6	10	6.2	2	3.4	5.3		5.9	ns	
t _{PLZ}	OE	AUB	1.9	5.6		6.2	2	3.7	5.3		5.9	115	
^t PZH	CE	A or B	1.2	5.5		7	1.3	3.2	5.3		6.8	no	
^t PZL	CE	AUID	1.2	5.5		7	1.3	3.5	5.3		6.8	ns	
^t PHZ	CE	A or B	2.2	5.7		6.2	2.3	3.8	5.4		5.9	no	
t _{PLZ}	CE	AUIB	2.2	5.7		5.9	2.3	3.9	5.4		5.6	ns	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

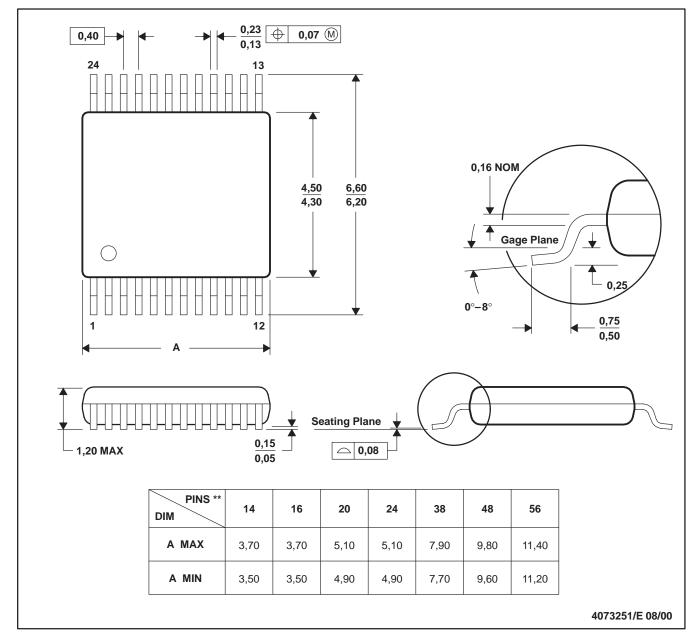
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \,\Omega$, $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

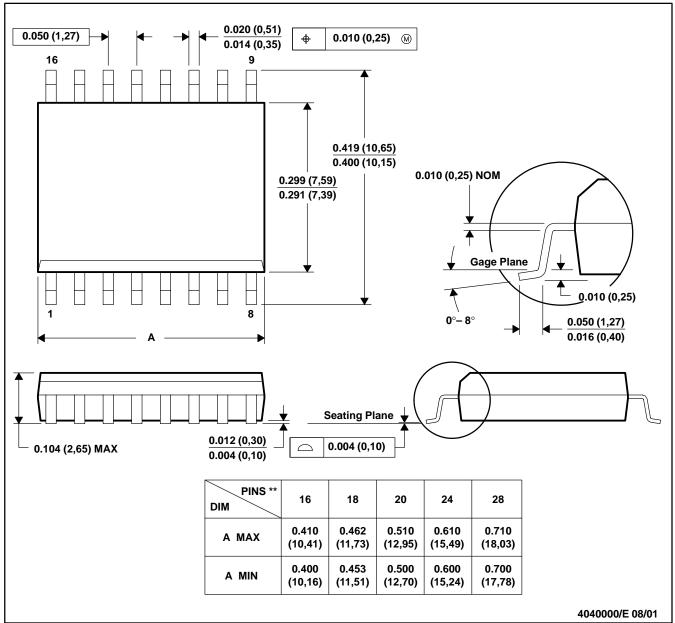
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



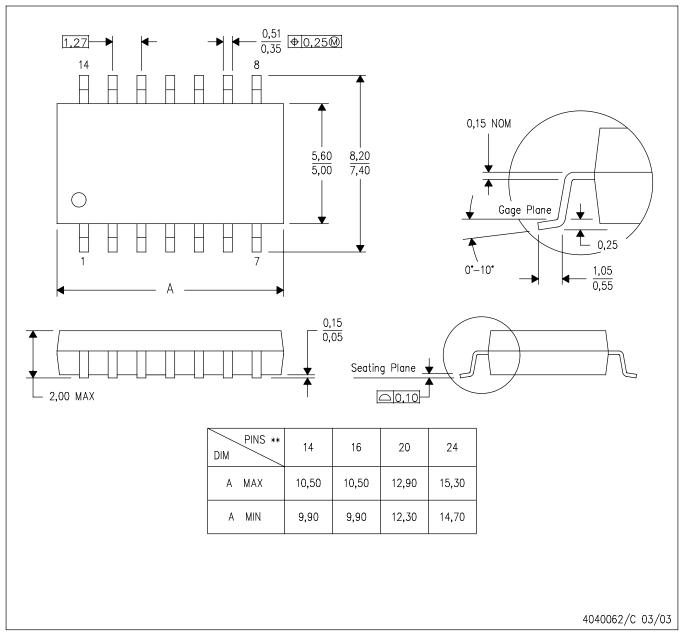
NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013

14-PIN SHOWN



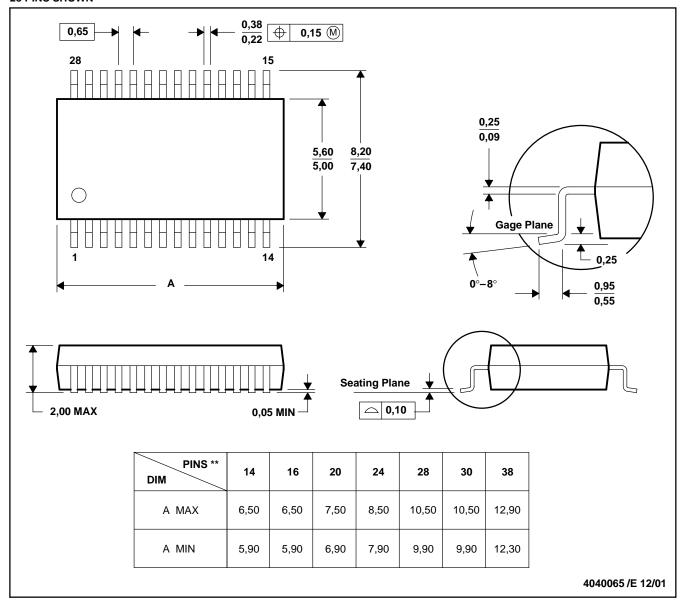
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

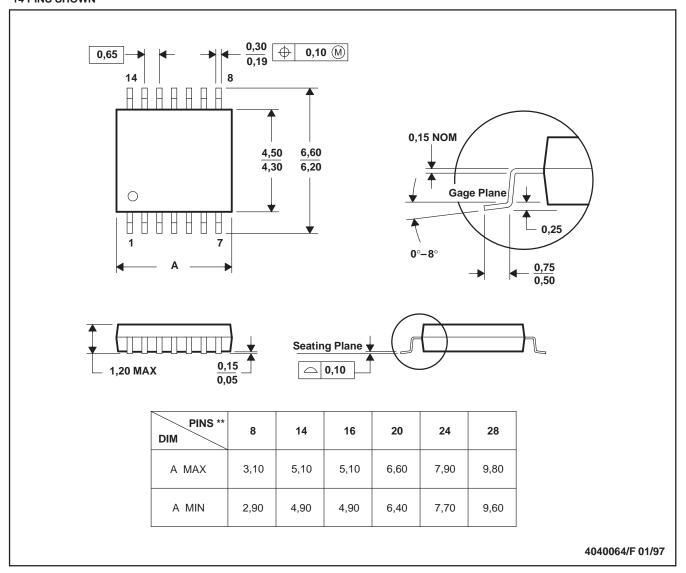
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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